IR-Lumineszenzdiode (940 nm) mit hoher Ausgangsleistung
High Power Infrared Emitter (940 nm)
Lead (Pb) Free Product - RoHS Compliant
SFH 4244



Wesentliche Merkmale

- Infrarot LED mit hoher Ausgangsleistung
- Kurze Schaltzeiten

Anwendungen

- Infrarotbeleuchtung für Kameras
- IR-Datenübertragung
- Sensorik

Sicherheitshinweise

Je nach Betriebsart emittieren diese Bauteile hochkonzentrierte, nicht sichtbare Infrarot-Strahlung, die gefährlich für das menschliche Auge sein kann. Produkte, die diese Bauteile enthalten, müssen gemäß den Sicherheits-richtlinien der IEC-Normen 60825-1 und 62471 behandelt werden.

Features

- High Power Infrared LED
- Short switching times

Applications

- Infrared Illumination for cameras
- IR Data Transmission
- Optical sensors

Safety Advices

Depending on the mode of operation, these devices emit highly concentrated non visible infrared light which can be hazardous to the human eye. Products which incorporate these devices have to follow the safety precautions given in IEC 60825-1 and IEC 62471.

Typ **Type**	**Bestellnummer** **Ordering Code**	**Strahlstärkegruppierung**[1] (I_F = 70 mA, t_p = 20 ms) **Radiant Intensity Grouping**[1] I_e (mW/sr)
SFH 4244	Q65110A7516	≥ 4 (typ. 11)

[1] gemessen bei einem Raumwinkel Ω = 0.01 sr / measured at a solid angle of Ω = 0.01 sr

Grenzwerte (T_A = 25 °C)
Maximum Ratings

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Betriebs- und Lagertemperatur Operating and storage temperature range	T_{op} , T_{stg}	– 40 … + 100	°C
Sperrspannung Reverse voltage	V_R	5	V
Vorwärtsgleichstrom Forward current	I_F	70	mA
Stoßstrom, t_p = 100 µs, D = 0 Surge current	I_{FSM}	700	mA
Verlustleistung Power dissipation	P_{tot}	140	mW
Wärmewiderstand Sperrschicht - Umgebung bei Montage auf FR4 Platine, Padgröße je 16 mm² Thermal resistance junction - ambient mounted on PC-board (FR4), padsize 16 mm² each	R_{thJA}	500	K/W
Wärmewiderstand Sperrschicht - Lötstelle bei Montage auf Metall-Block Thermal resistance junction - soldering point, mounted on metal block	R_{thJS}	280	K/W

Kennwerte (T_A = 25 °C)
Characteristics

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Wellenlänge der Strahlung Wavelength at peak emission I_F = 70 mA	λ_{peak}	950	nm
Centroid-Wellenlänge der Strahlung Centroid wavelength I_F = 70 mA	$\lambda_{centroid}$	940	nm
Spektrale Bandbreite bei 50% von I_{max} Spectral bandwidth at 50% of I_{max} I_F = 70 mA	$\Delta\lambda$	42	nm
Abstrahlwinkel Half angle	φ	± 60	Grad deg.
Aktive Chipfläche Active chip area	A	0.04	mm²

Kennwerte (T_A = 25 °C)
Characteristics (cont'd)

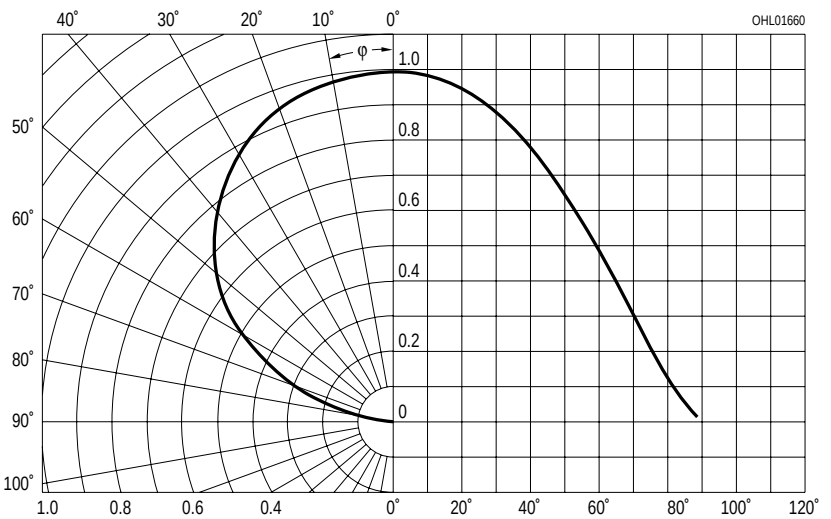
Bezeichnung **Parameter**	**Symbol** **Symbol**	**Wert** **Value**	**Einheit** **Unit**
Abmessungen der aktiven Chipfläche Dimension of the active chip area	$L \times B$ $L \times W$	0.2 × 0.2	mm²
Schaltzeiten, I_e von 10% auf 90% und von 90% auf 10%, bei I_F = 70 mA, R_L = 50 Ω Switching times, I_e from 10% to 90% and from 90% to 10%, I_F = 70 mA, R_L = 50 Ω	t_r, t_f	11	ns
Durchlassspannung Forward voltage I_F = 70 mA, t_p = 20 ms I_F = 500 mA, t_p = 100 µs	 V_F V_F	 1.6 (< 2.0) 2.4 (< 3.0)	 V V
Sperrstrom Reverse current	I_R	not designed for reverse operation	µA
Gesamtstrahlungsfluss Total radiant flux I_F = 70 mA, t_p = 20 ms	$\Phi_{e\ typ}$	33	mW
Temperaturkoeffizient von I_e bzw. Φ_e, I_F = 70 mA Temperature coefficient of I_e or Φ_e, I_F = 70 mA	TC_I	– 0.5	%/K
Temperaturkoeffizient von V_F, I_F = 70 mA Temperature coefficient of V_F, I_F = 70 mA	TC_V	– 3.5	mV/K
Temperaturkoeffizient von λ, I_F = 70 mA Temperature coefficient of λ, I_F = 70 mA	TC_λ	+ 0.3	nm/K

Strahlstärke I_e in Achsrichtung[1)]
gemessen bei einem Raumwinkel Ω = 0.01 sr
Radiant Intensity I_e in Axial Direction
at a solid angle of Ω = 0.01 sr

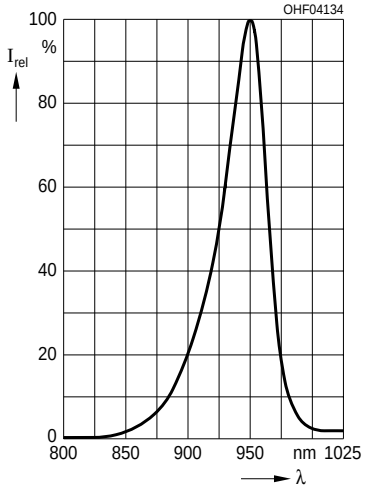
Bezeichnung Parameter	Symbol	Werte Values			Einheit Unit
		SFH 4244-P	SFH 4244-Q	SFH 4244-R	
Strahlstärke Radiant intensity I_F = 70 mA, t_p = 20 ms	$I_{e\ min}$ $I_{e\ max}$	4 8	6.3 12.5	10 20	mW/sr mW/sr
Strahlstärke Radiant intensity I_F = 500 mA, t_p = 25 µs	$I_{e\ typ}$	30	47	75	mW/sr

[1)] Nur eine Gruppe in einer Verpackungseinheit (Streuung kleiner 2:1) /
Only one bin in one packing unit (variation lower 2:1)

Abstrahlcharakteristik
Radiation Characteristics $I_{rel} = f(\varphi)$

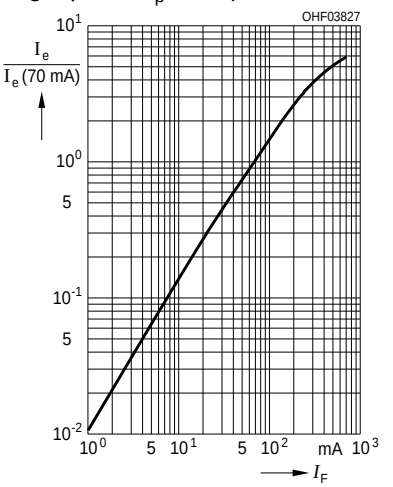


Relative Spectral Emission
$I_{rel} = f(\lambda)$

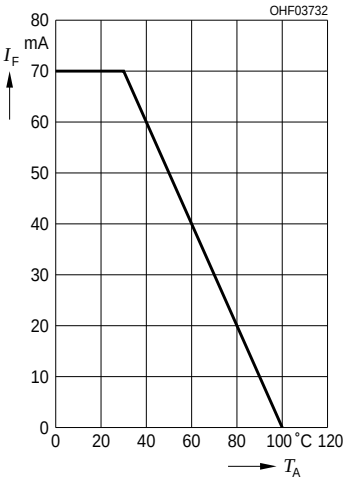


Radiant Intensity $\frac{I_e}{I_e\ 70\ mA} = f(I_F)$

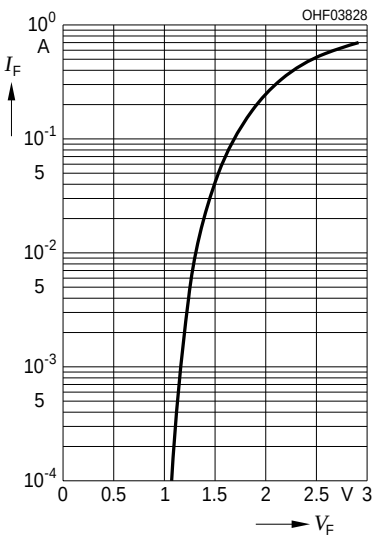
Single pulse, t_p = 25 µs



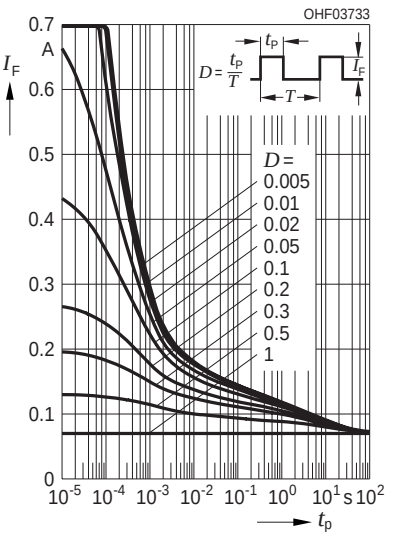
Max. Permissible Forward Current
$I_F = f(T_A)$, R_{thJA} = 500 K/W



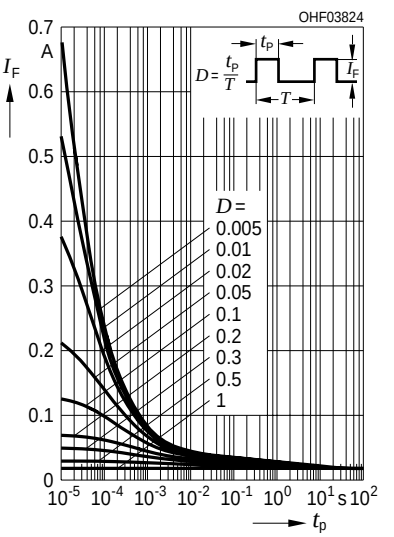
Forward Current $I_F = f(V_F)$
Single pulse, t_p = 100 µs



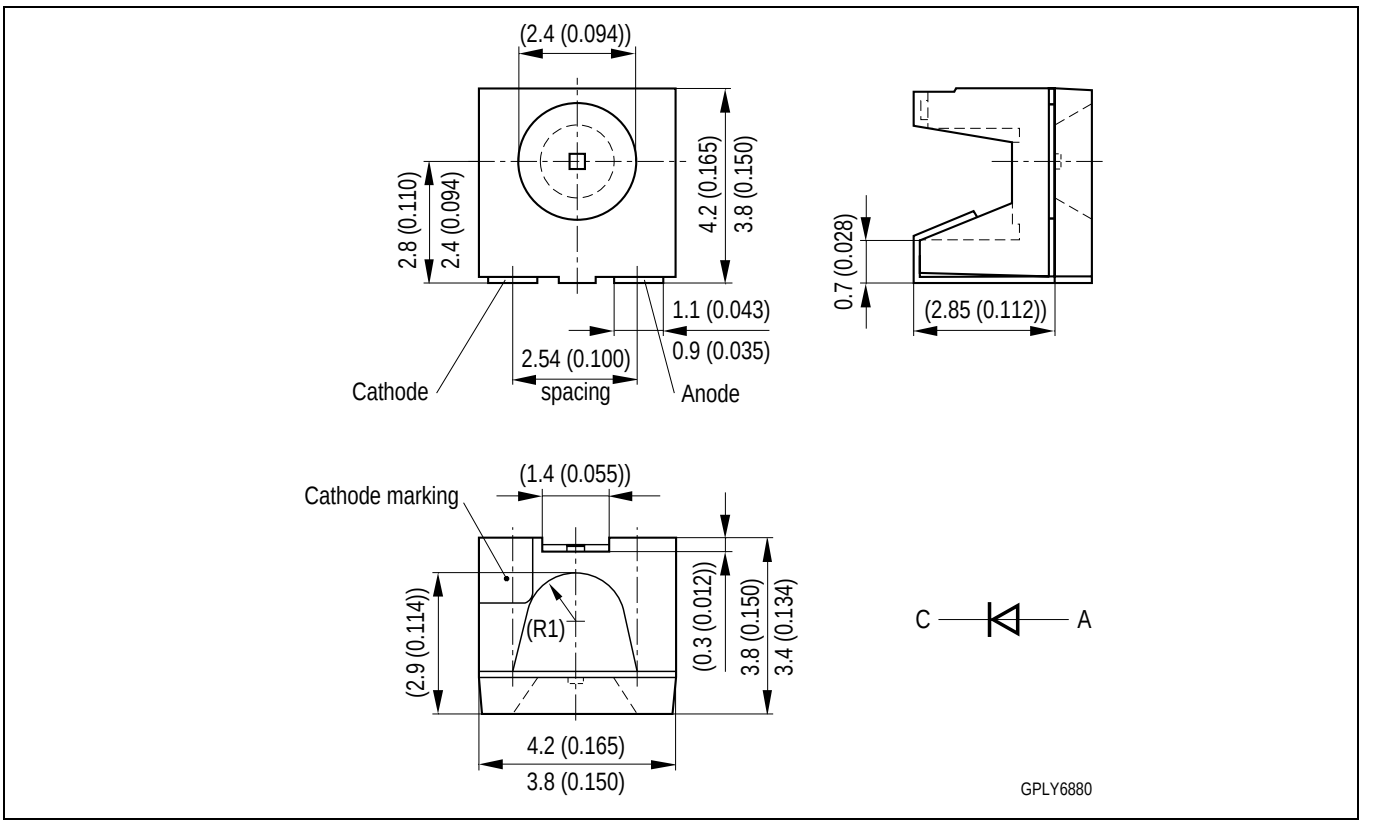
Permissible Pulse Handling Capability $I_F = f(\tau)$, T_A = 25 °C, duty cycle D = parameter



Permissible Pulse Handling Capability $I_F = f(\tau)$, T_A = 85 °C, duty cycle D = parameter



Maßzeichnung
Package Outlines

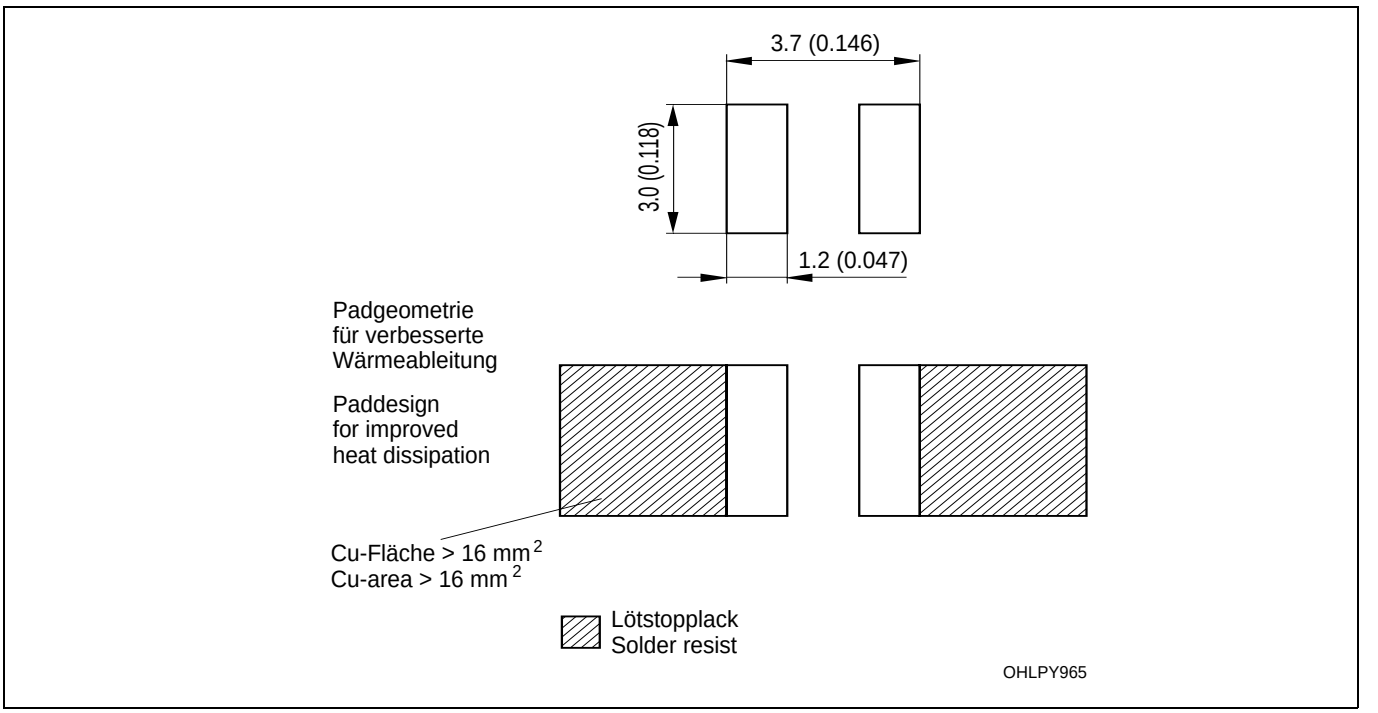


Maße in mm (inch) / Dimensions in mm (inch).

Gehäuse / Package	SIDELED®, klarer Verguss / SIDELED®, clear resin
Anschlussbelegung Pin configuration	Kathode: abgeschrägte Ecke Cathode: beveled edge

Empfohlenes Lötpaddesign
Recommended Solder Pad Design

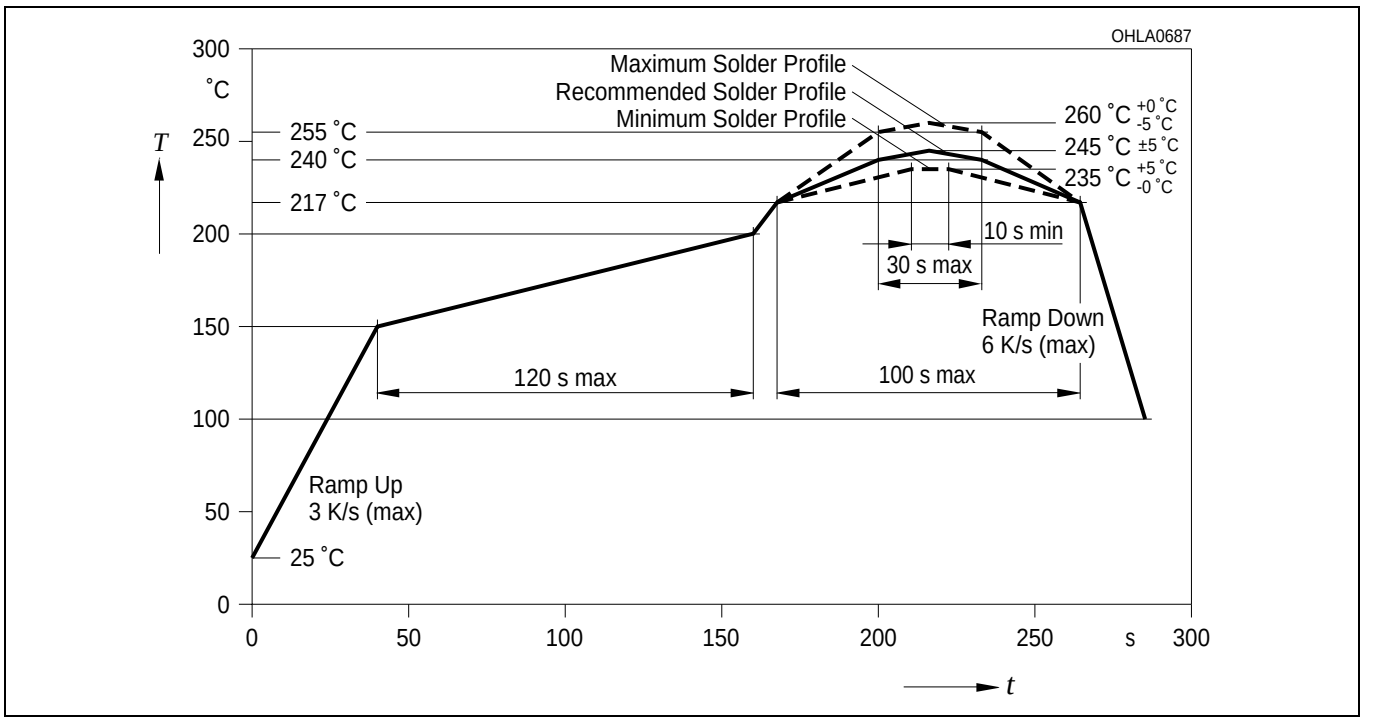
Reflow Löten
Reflow Soldering



Maße in mm (inch) / Dimensions in mm (inch).

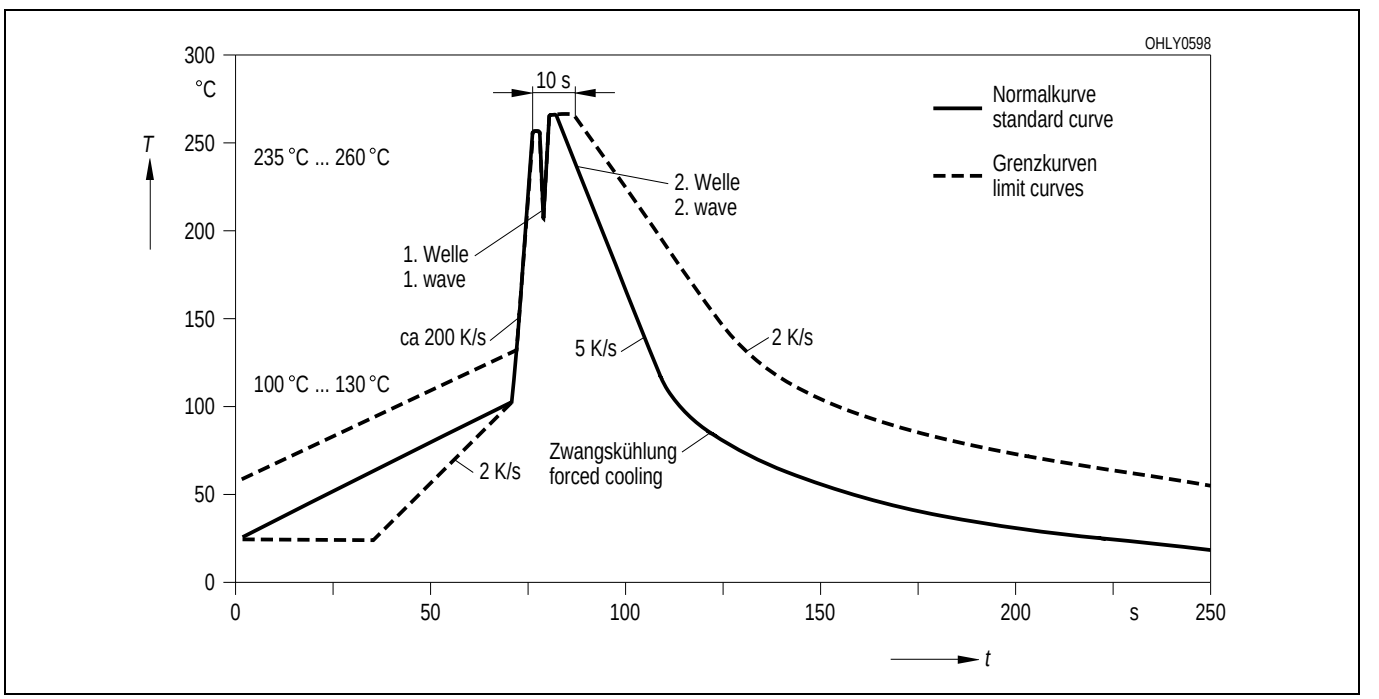
Lötbedingungen
Soldering Conditions
Reflow Lötprofil für bleifreies Löten
Reflow Soldering Profile for lead free soldering

Vorbehandlung nach JEDEC Level 2
Preconditioning acc. to JEDEC Level 2
(nach J-STD-020C)
(acc. to J-STD-020C)



Wellenlöten (TTW)
TTW Soldering

(nach CECC 00802)
(acc. to CECC 00802)



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[1] A critical component is a component usedin a life-support device or system whose failure can reasonably be expected to cause the failure of that life-support device or system, or to affect its safety or effectiveness of that device or system.

[2] Life support devices or systems are intended (a) to be implanted in the human body, or (b) to support and/or maintain and sustain human life. If they fail, it is reasonable to assume that the health of the user may be endangered.

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Related Product Links

720-SFH4244-Z - Osram Opto Semiconductor SFH 4244-Z